

Product specifications

Part number ⁶	OCL ¹ (μH) $\pm 20\%$	FLL ² (μH) minimum	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C	SRF (MHz) typical	K-factor ⁵
HCM1A0703V2-R10-R	0.10	0.064	29	54	0.63	0.8	350	1284
HCM1A0703V2-R15-R	0.15	0.090	24	30	1.03	1.3	195	1541
HCM1A0703V2-R22-R	0.22	0.130	18	32	1.8	2.3	150	1039
HCM1A0703V2-R33-R	0.33	0.210	15	19	2.9	3.5	95	823
HCM1A0703V2-R47-R	0.47	0.300	13	17	3.7	4.14	70	713
HCM1A0703V2-R56-R	0.56	0.350	13	12	3.8	4.5	60	805
HCM1A0703V2-R68-R	0.68	0.430	12	13	4.8	5.5	57	843
HCM1A0703V2-R82-R	0.82	0.520	10	14	5.7	6.6	55	608
HCM1A0703V2-1R0-R	1.0	0.64	10	9.0	6.5	7.8	48	627
HCM1A0703V2-1R2-R	1.2	0.76	9	12	8.6	9.9	35	434
HCM1A0703V2-1R5-R	1.5	0.96	8.5	10	9.5	11.5	35	445
HCM1A0703V2-2R2-R	2.2	1.40	7.0	8.5	12.5	15.5	29	532
HCM1A0703V2-3R3-R	3.3	2.10	5.0	7.5	24.5	28.5	25	281
HCM1A0703V2-4R7-R	4.7	3.00	4.0	6.8	40.3	46.5	20	227
HCM1A0703V2-6R8-R	6.8	4.30	3.6	5.6	54	65	16	276
HCM1A0703V2-8R2-R	8.2	5.20	3.5	4.8	53	64	14	173
HCM1A0703V2-100-R	10	6.40	3.3	4.4	65	75	12	177
HCM1A0703V2-150-R	15	9.60	2.6	3.6	96	110	9.5	147
HCM1A0703V2-220-R	22	14.1	2.0	2.9	135	149	7.0	134
HCM1A0703V2-330-R	33	19.8	1.6	2.3	200	242	6.5	92

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc, +25 °C

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{rms}, I_{sat}, +25 °C

3. I_{sat}: DC current for an approximate temperature rise of 30 °C without core loss. Derating is necessary for AC currents.

PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +155 °C under worst case operating conditions verified in the end application.

4. I_{sat}: Peak current for approximately 20% rolloff @ +25 °C

5. K-factor: Used to determine B_{pp} for core loss (see graph). B_{pp} = K * L * ΔI . B_{pp}: (Gauss), K: (K-factor from table),

L: (Inductance in μH), ΔI (Peak to peak ripple current in Amps).

6. Part Number Definition: HCM1A0703V2-xxx-R

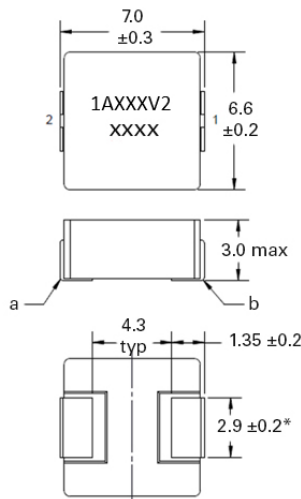
HCM1A0703V2 = Product code and size

xxx= inductance value in μH , R= decimal point,

If no R is present then last character equals number of zeros

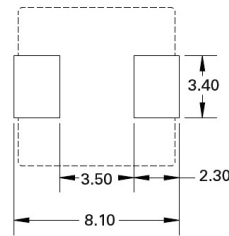
-R suffix = RoHS compliant

Dimensions (mm)

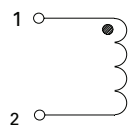


* HCM1A0703V2-R22-R (2.5 ±0.2)

Recommended pad layout



Schematic



Part marking: 1AxxxV2, xxx=inductance value in μH , R=decimal point. If no R is present then last character equals number of zeros. xxxx=Lot code

All soldering surfaces to be coplanar within 0.1 millimeters

Tolerances are ±0.3 millimeters unless stated otherwise

Pad layout tolerances are ±0.1 millimeters unless stated otherwise

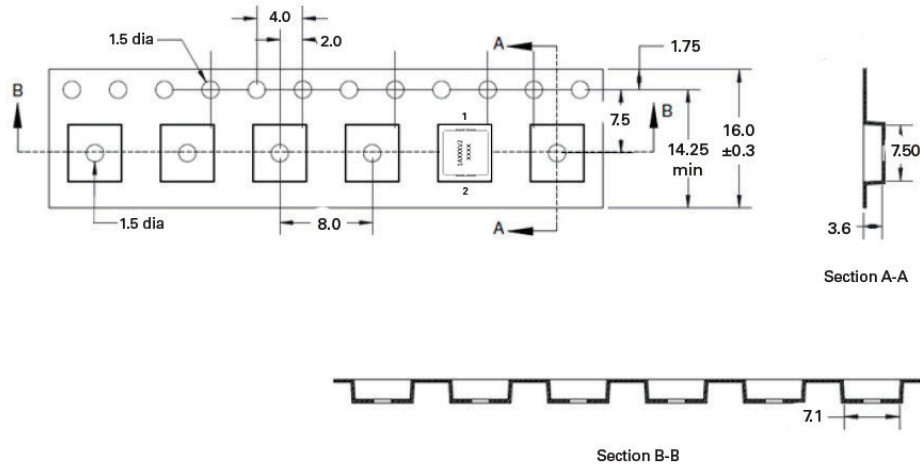
DCR measured from point "a" to point "b"

Do not route traces or vias underneath the inductor

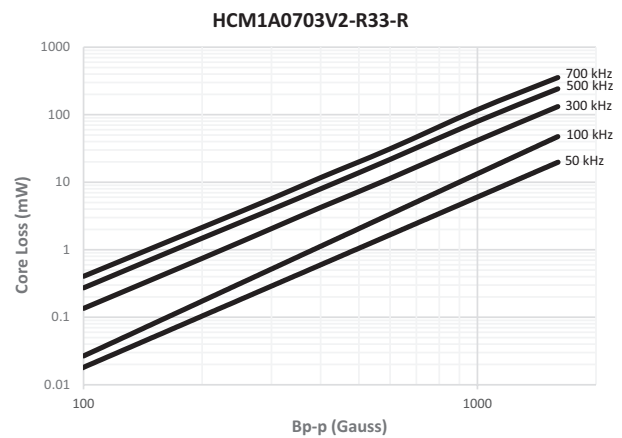
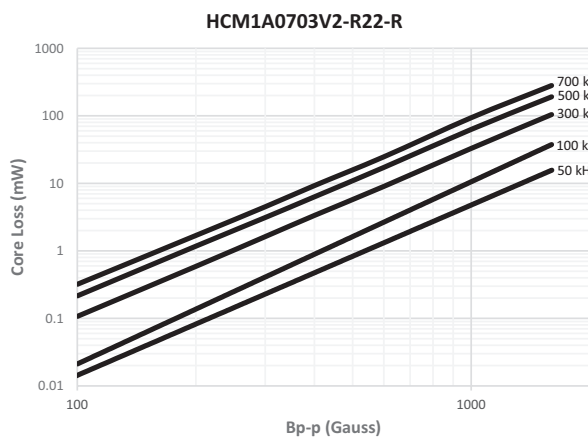
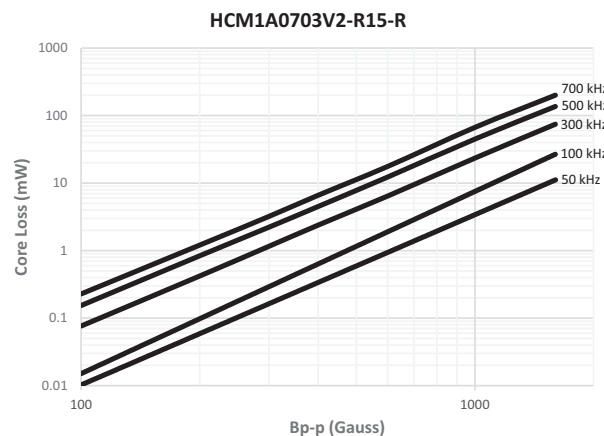
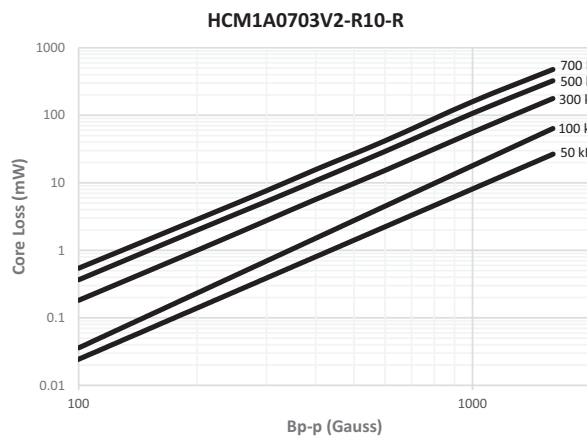
Packaging information (mm)

Drawing not to scale

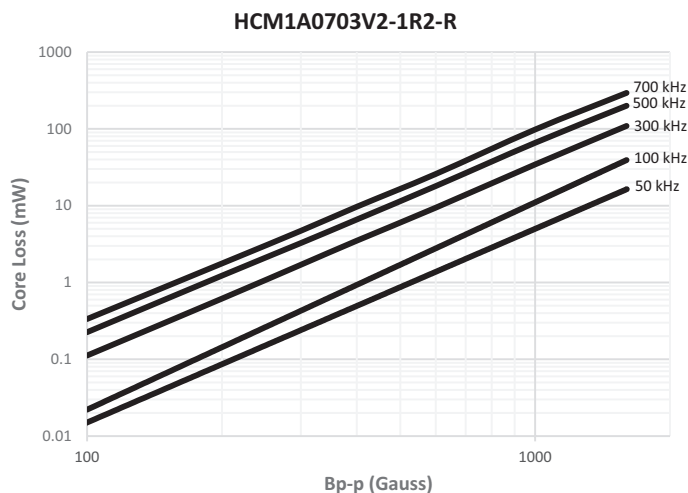
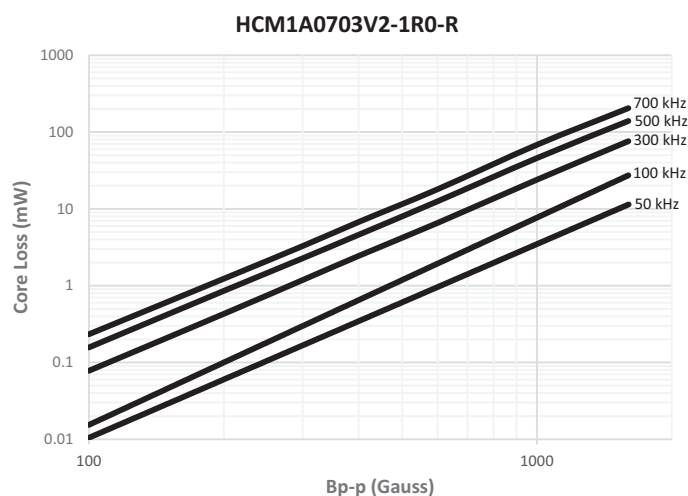
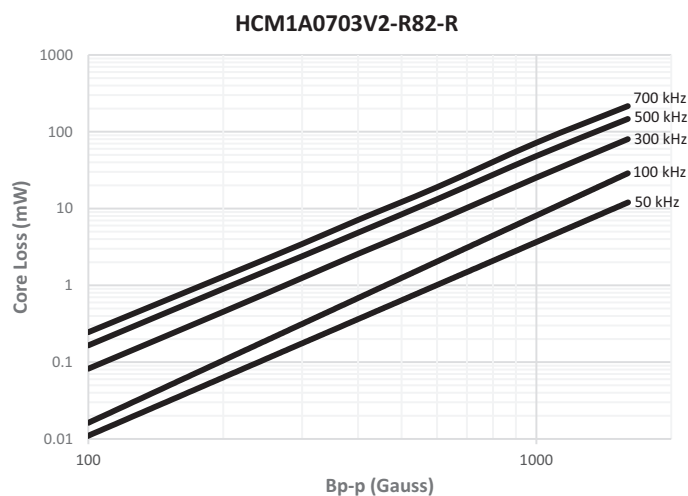
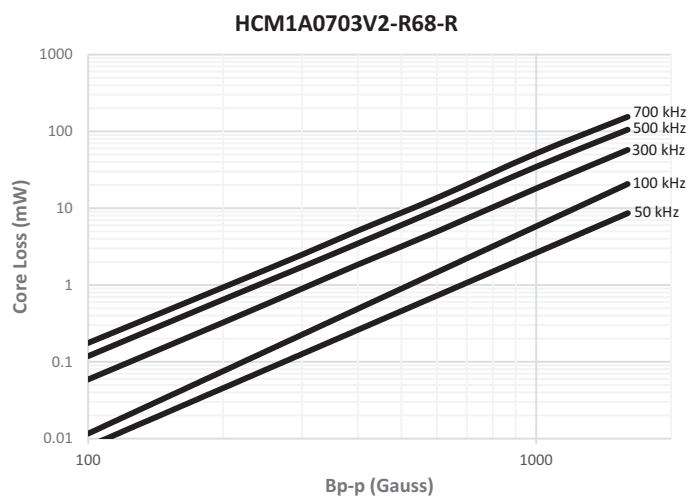
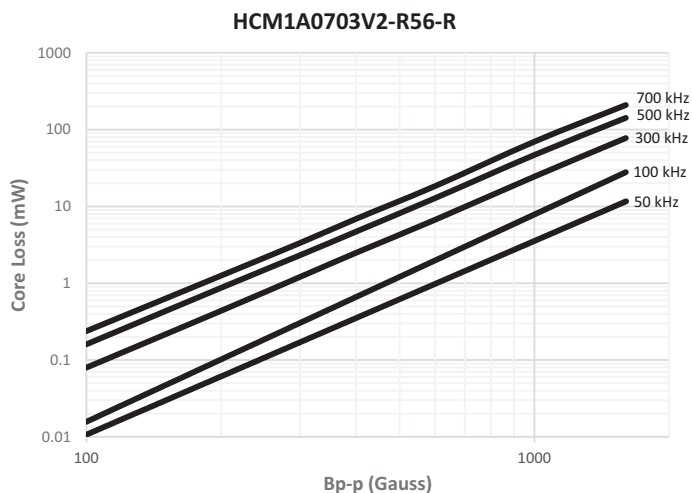
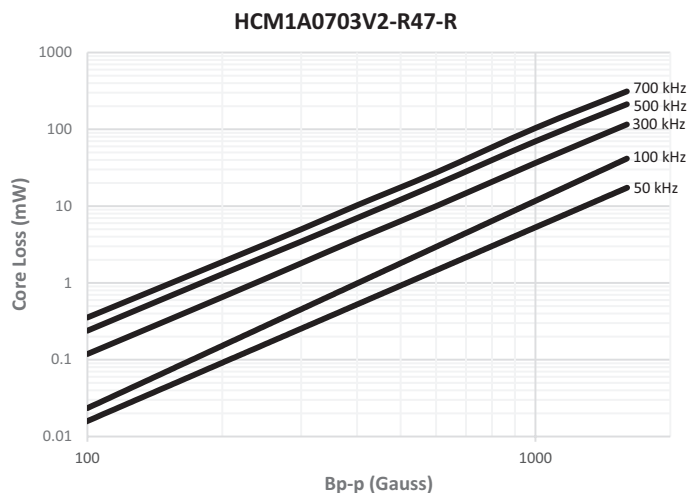
Supplied in tape and reel packaging, 2000 parts per 13" diameter reel



Core loss vs B_{p-p}

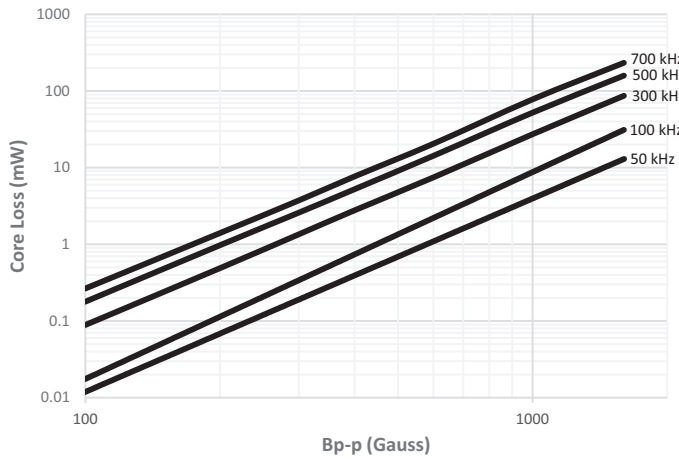


Core loss vs B_{p-p}

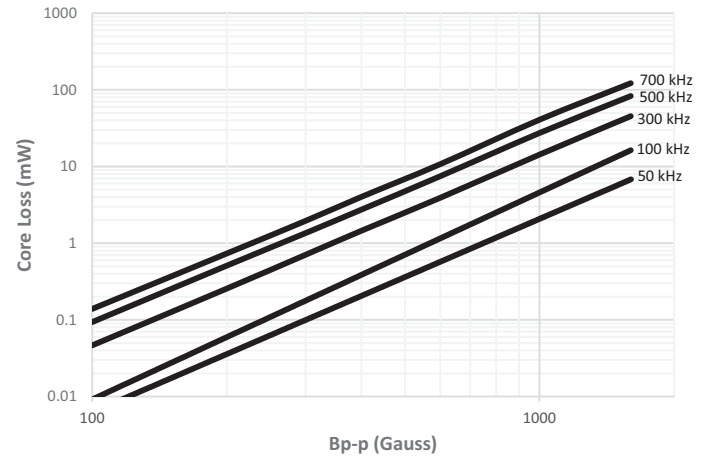


Core loss vs B_{p-p}

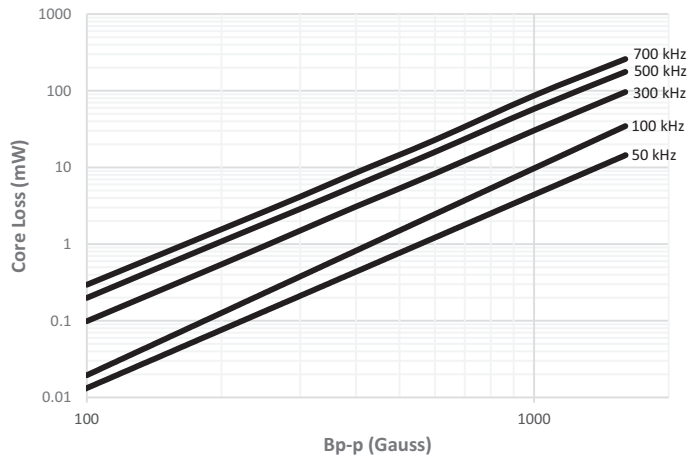
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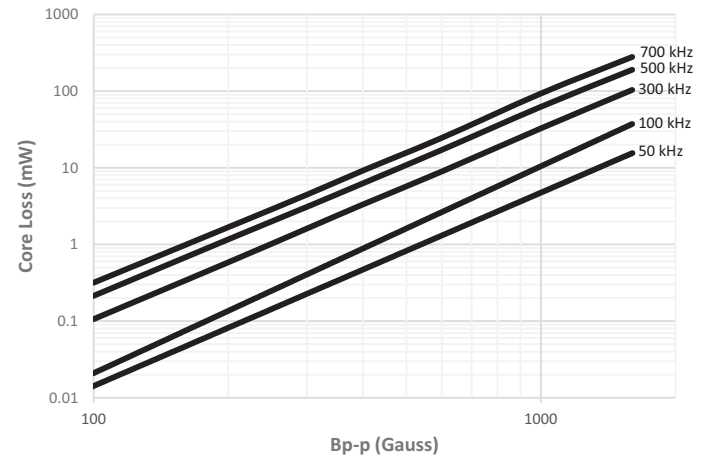
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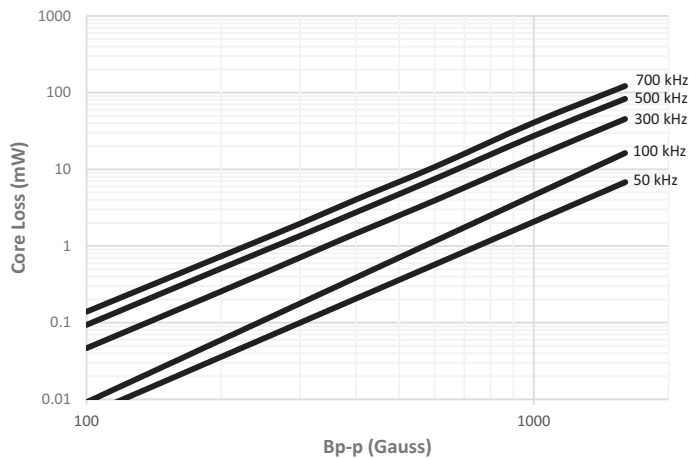
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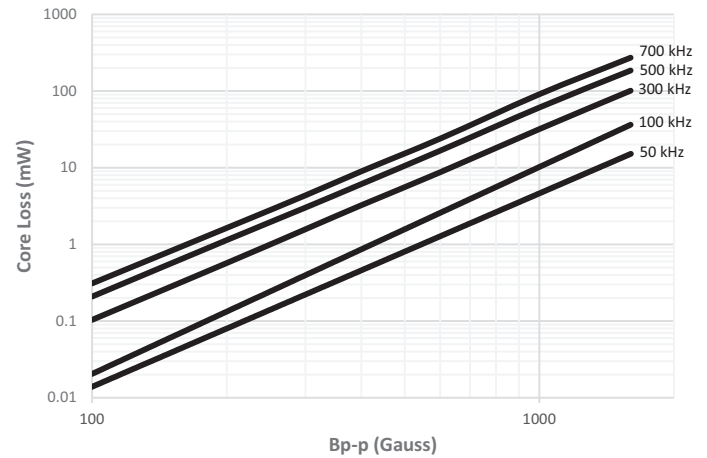
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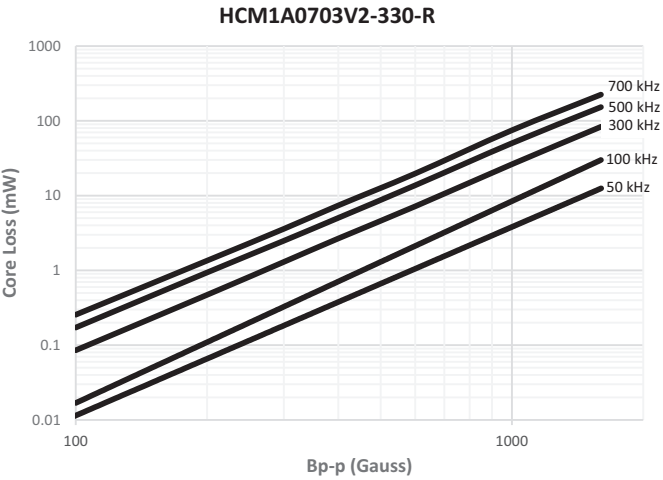
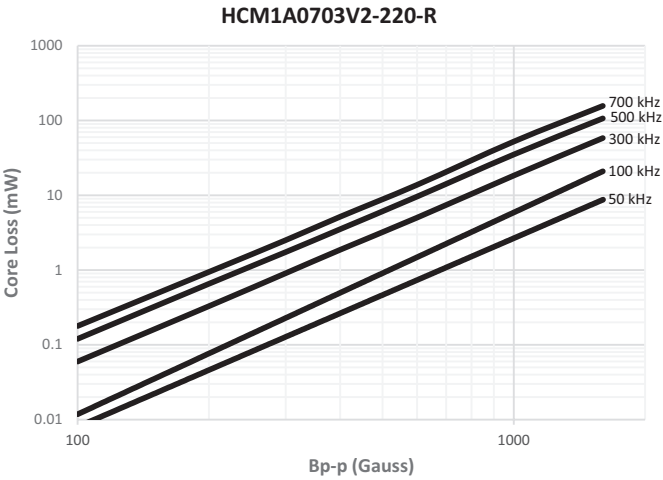
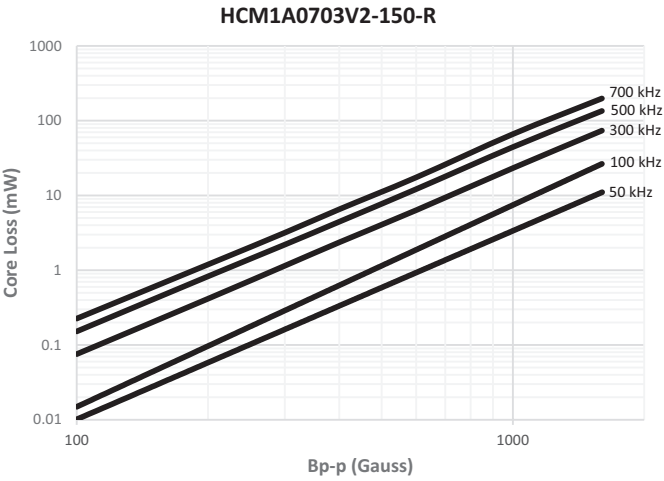
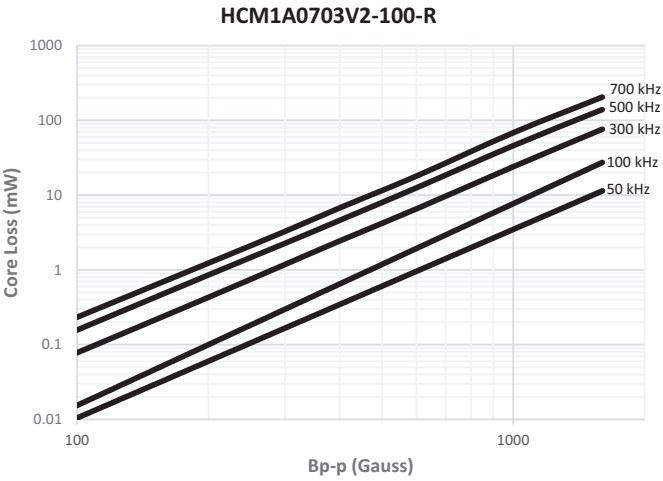
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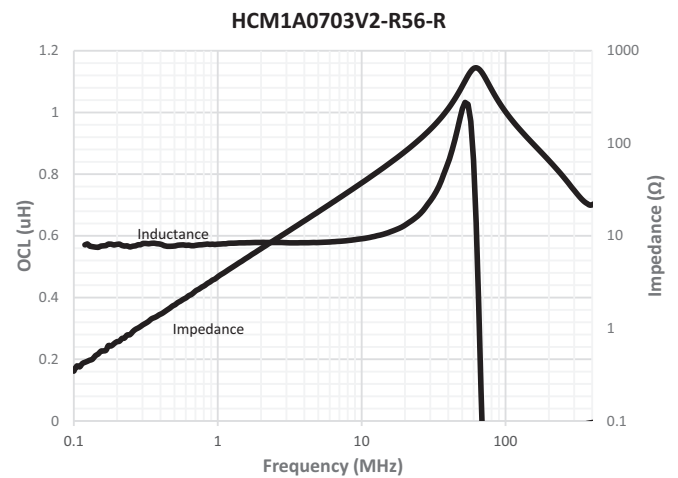
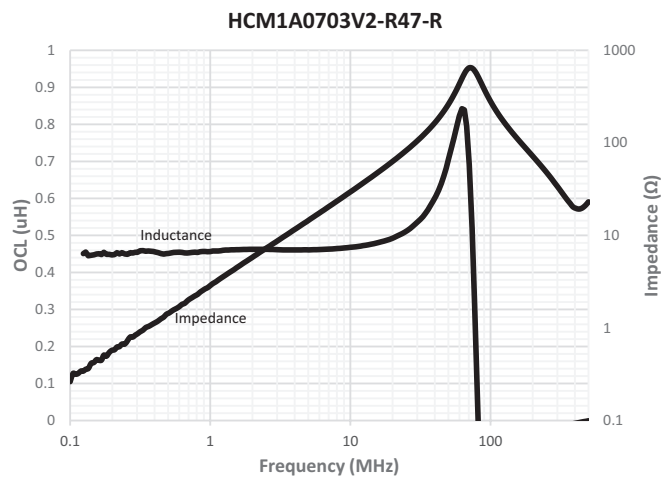
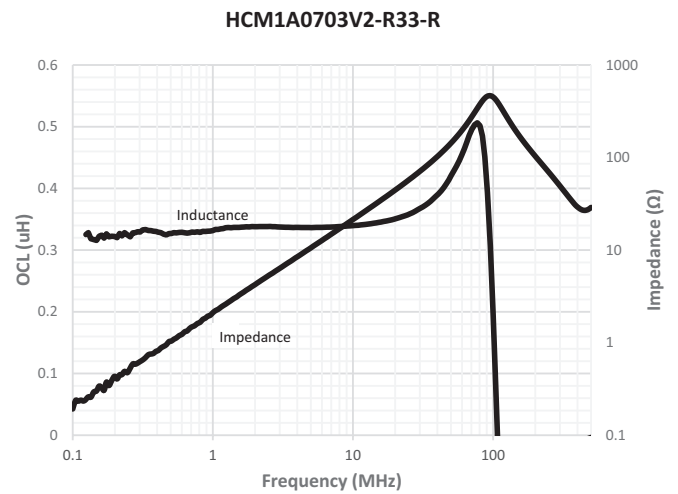
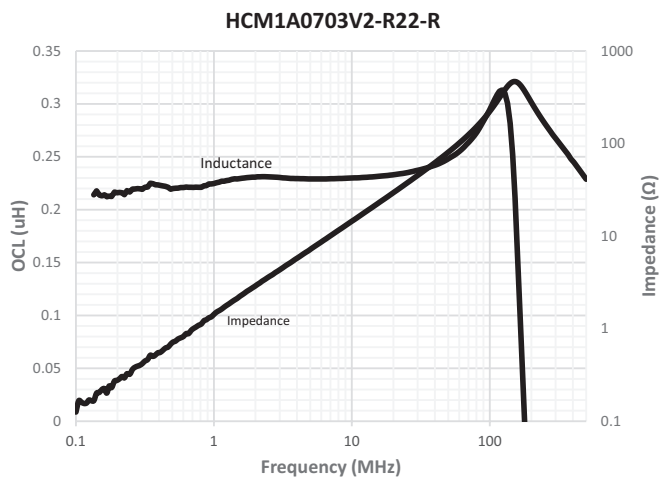
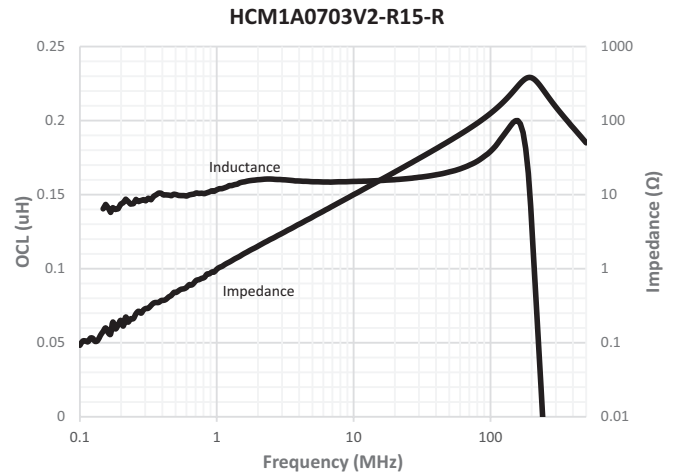
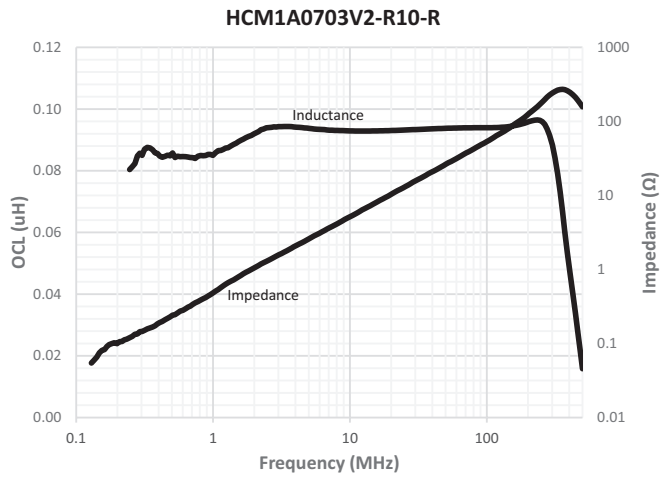
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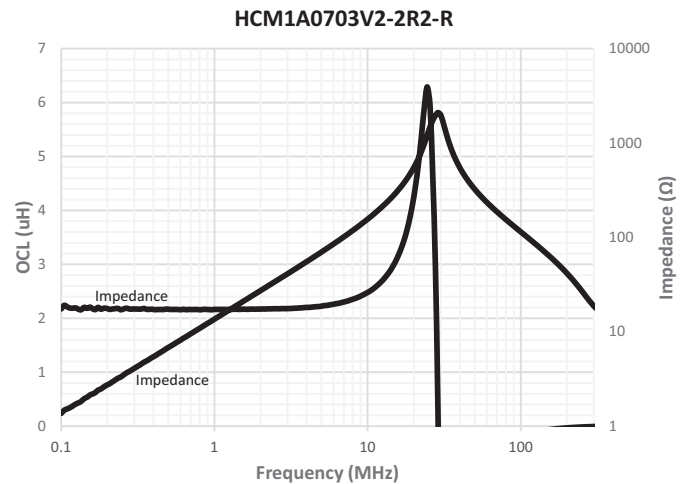
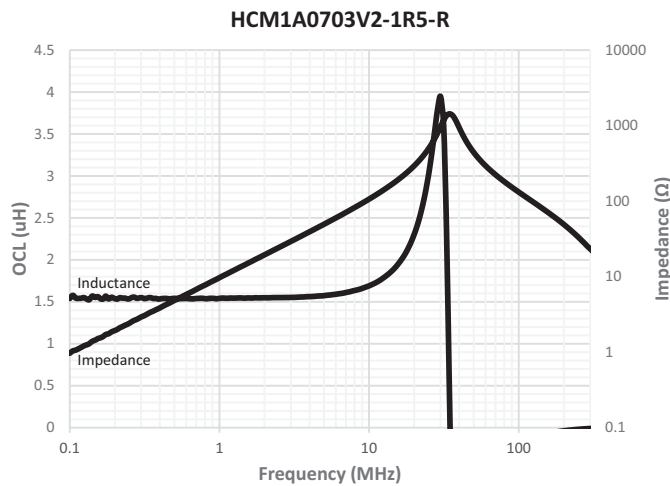
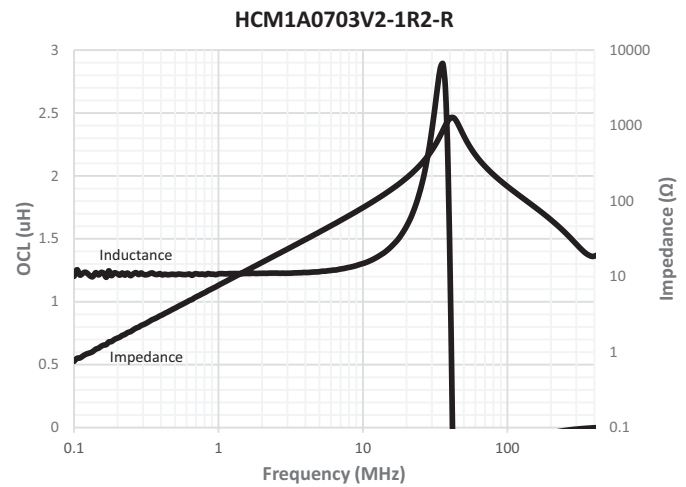
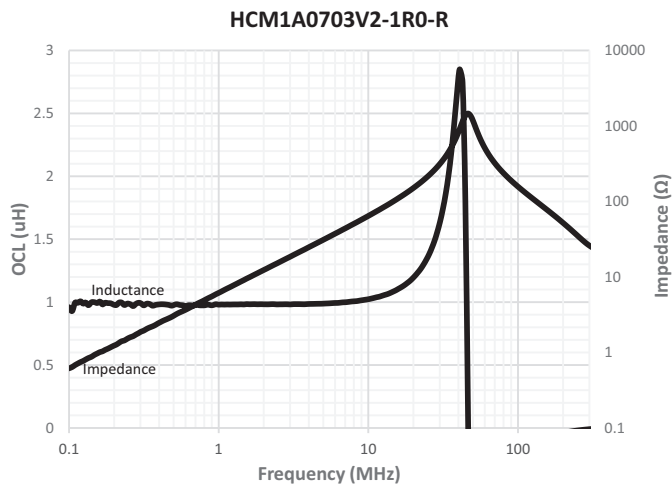
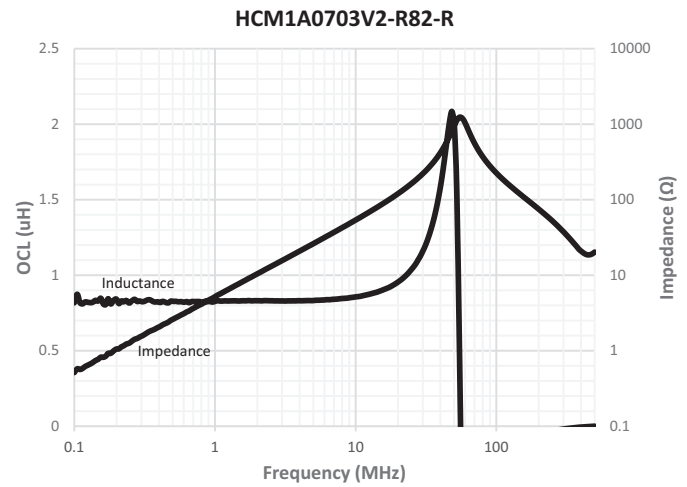
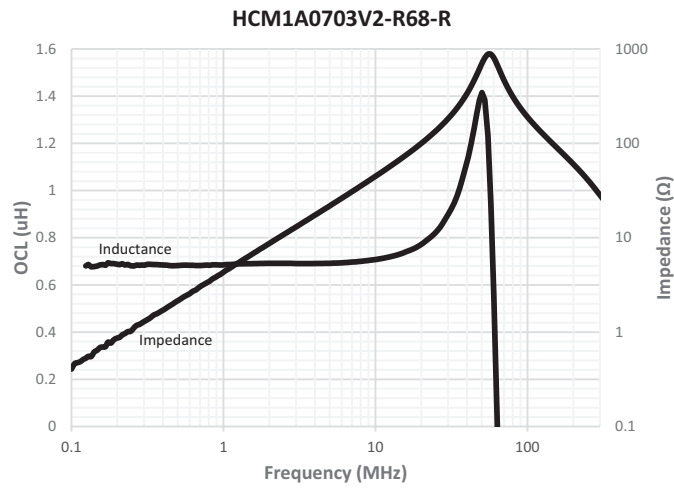
Core loss vs B_{p-p}



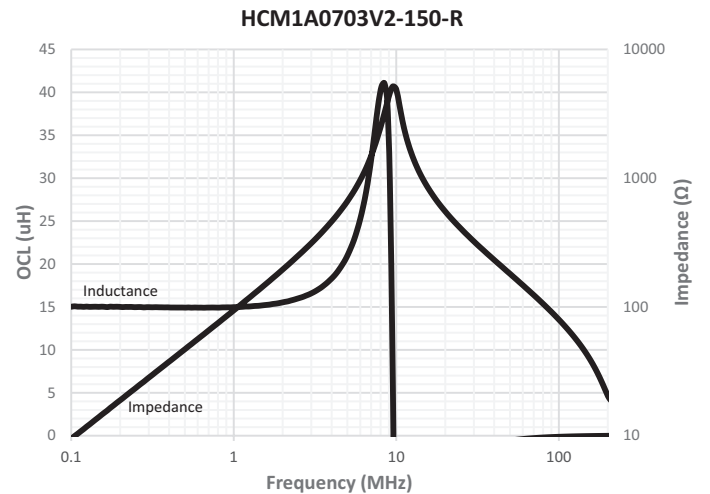
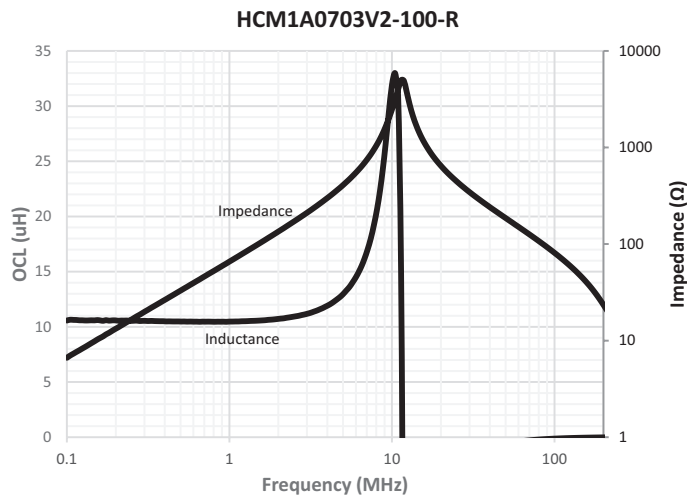
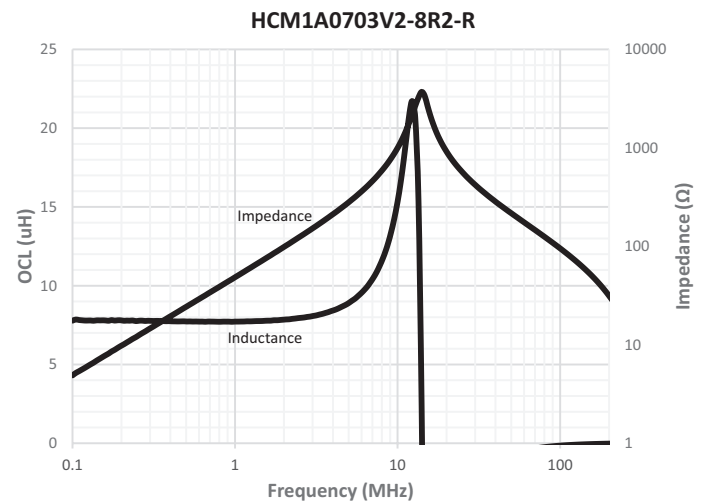
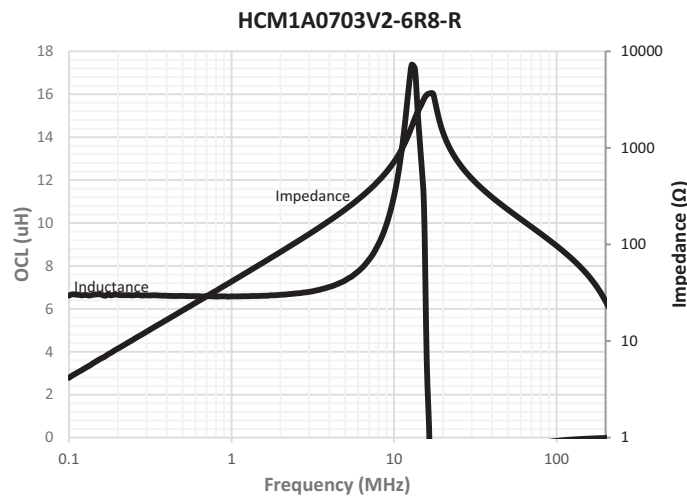
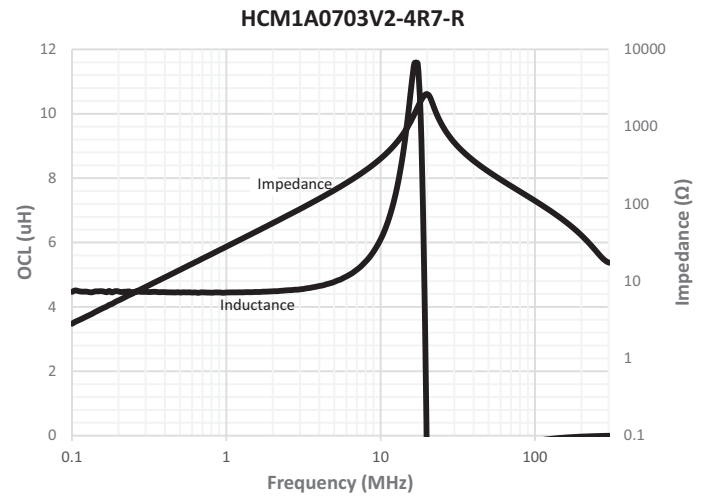
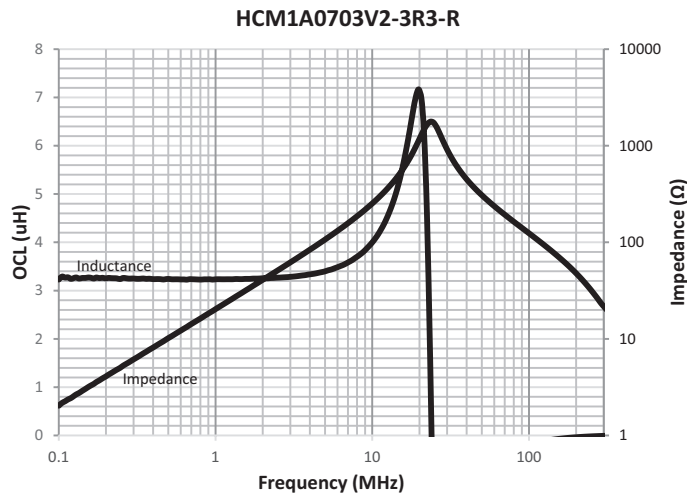
Inductance and impedance vs. frequency



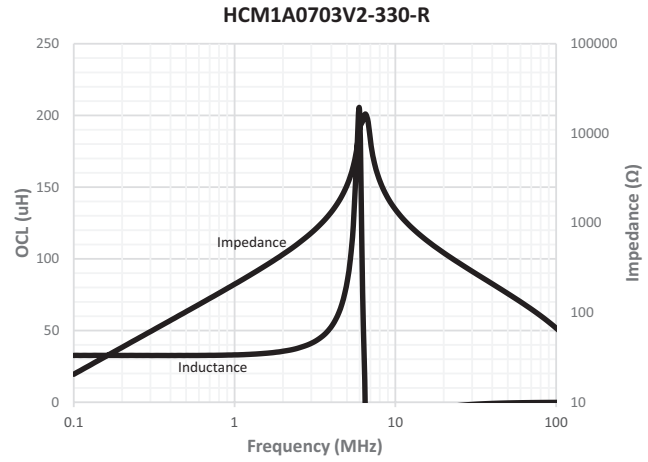
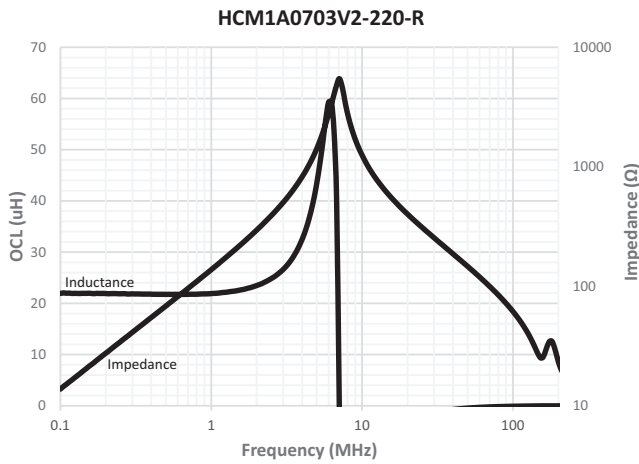
Inductance and impedance vs. frequency



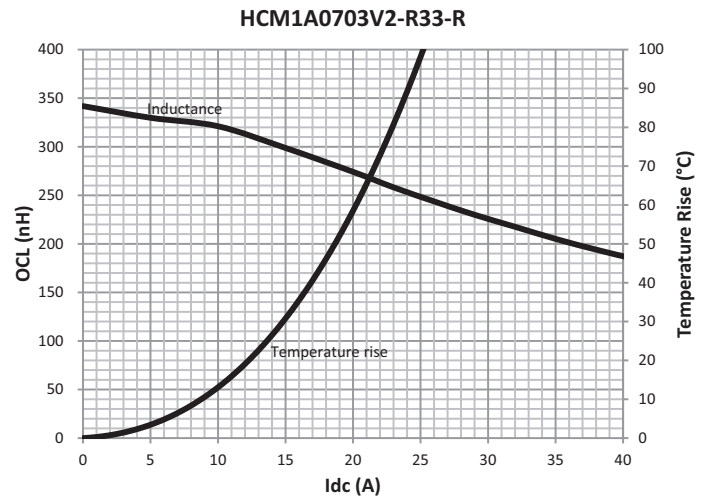
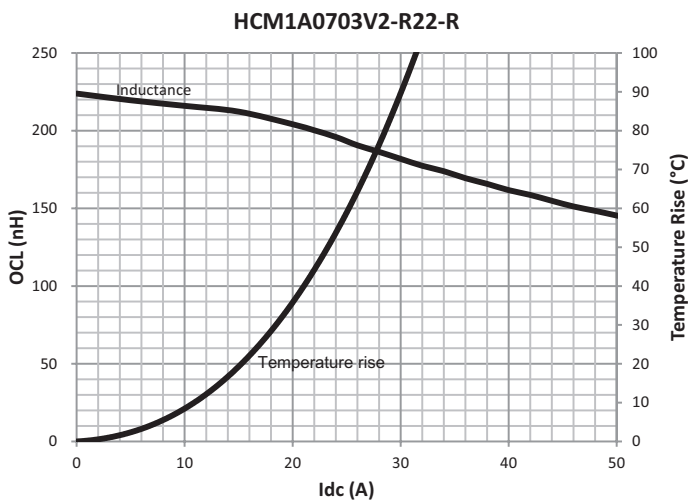
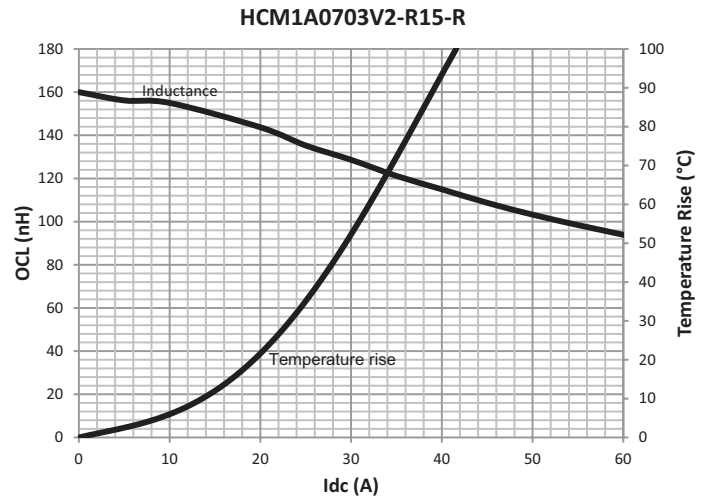
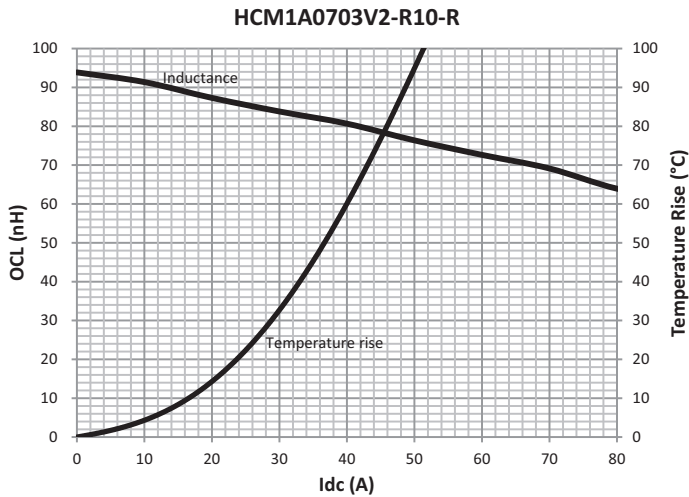
Inductance and impedance vs. frequency



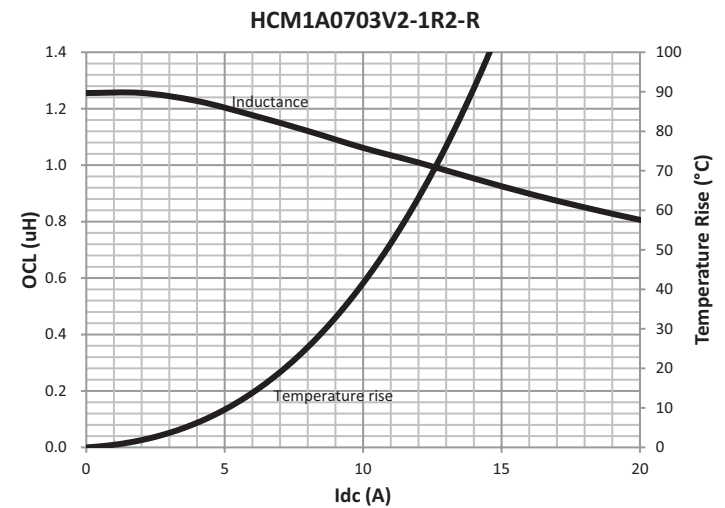
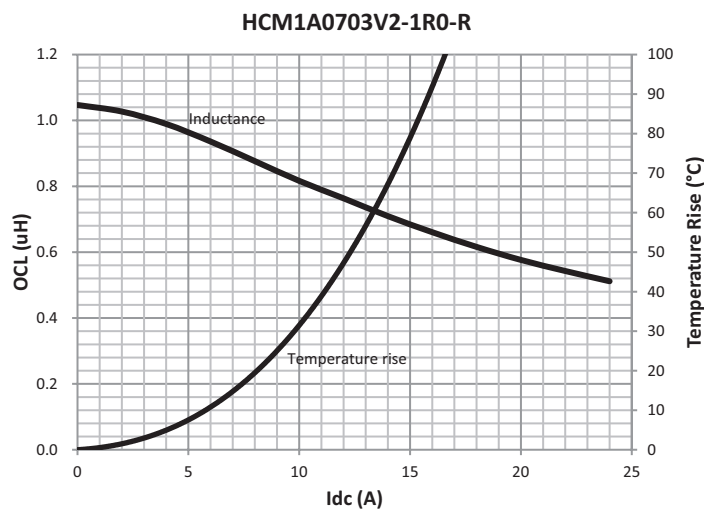
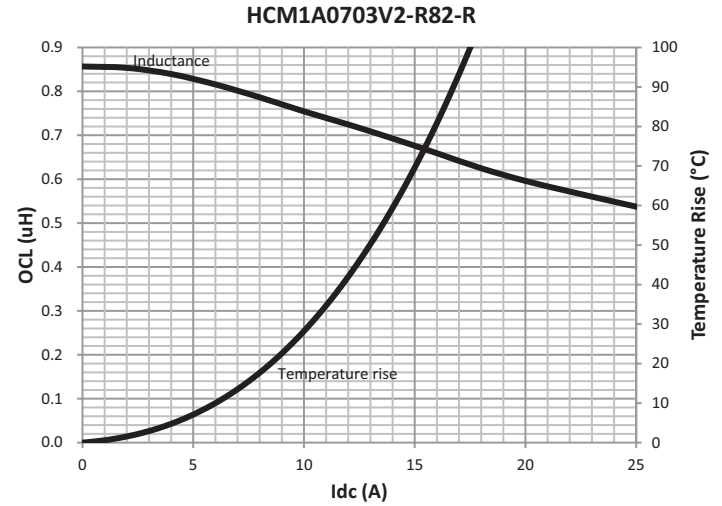
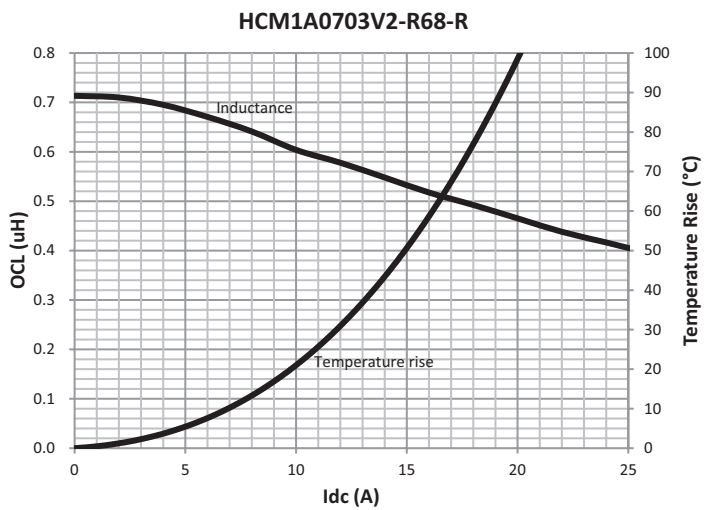
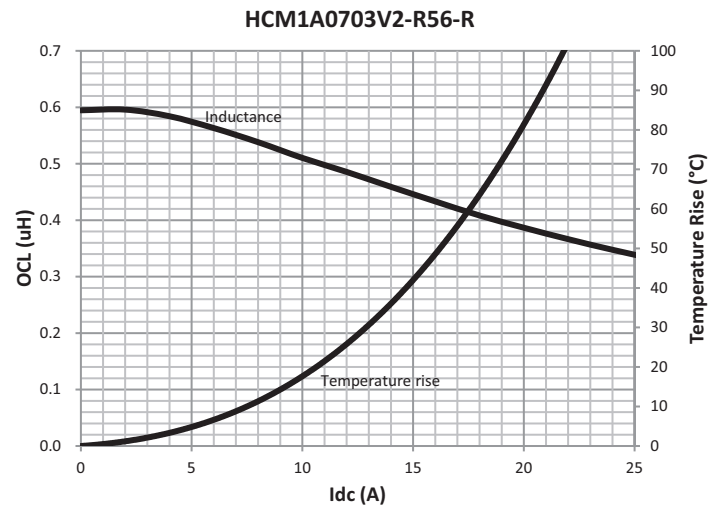
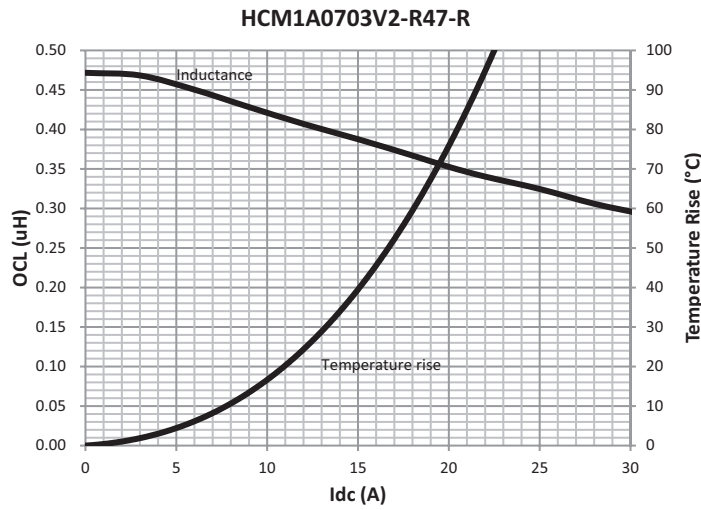
Inductance and impedance vs. frequency



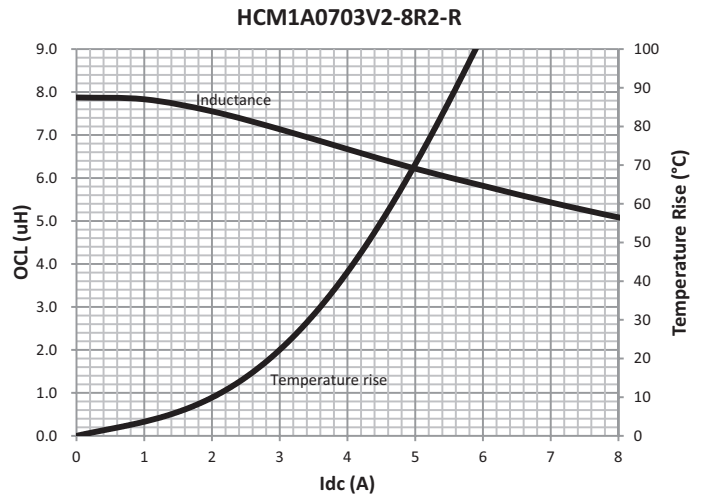
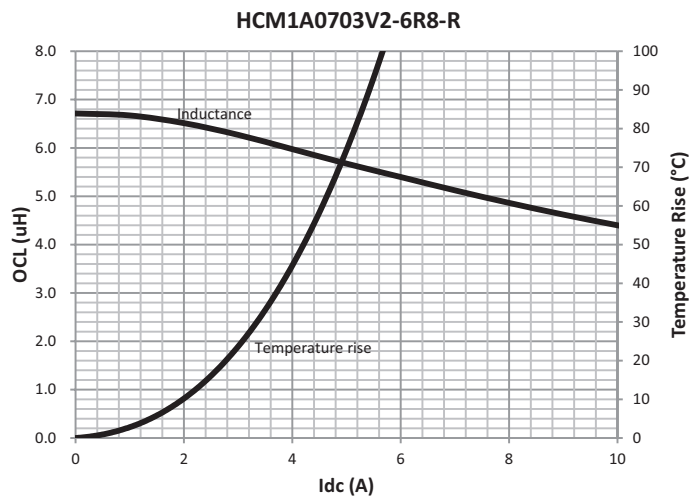
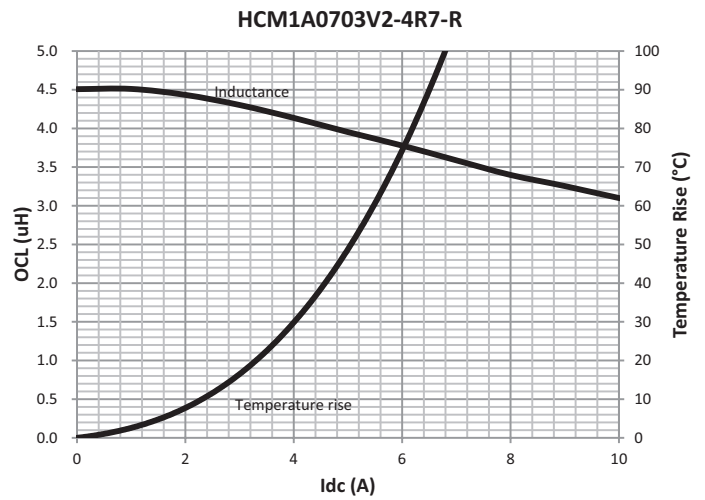
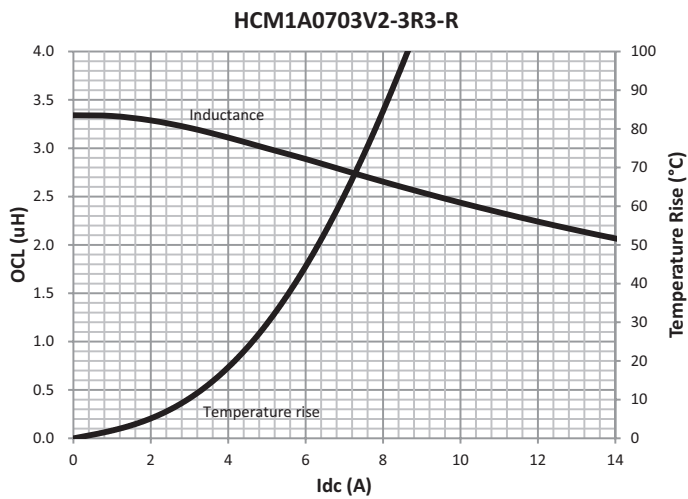
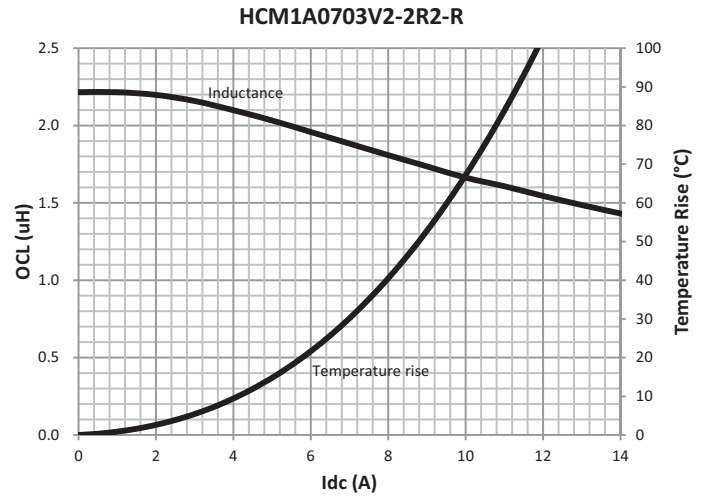
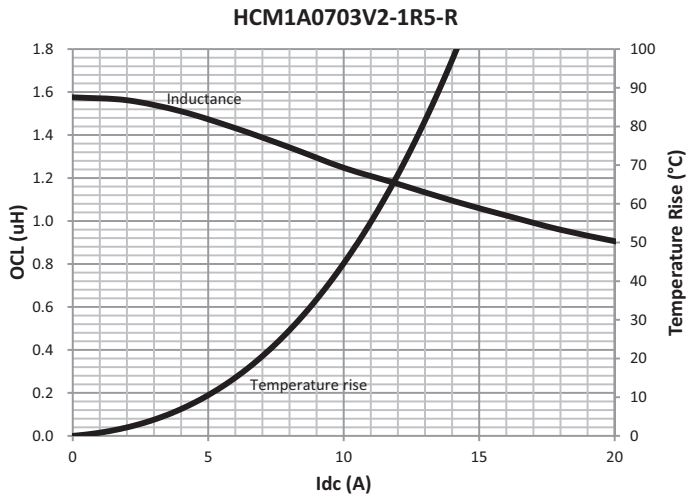
Inductance and temperature rise vs. current



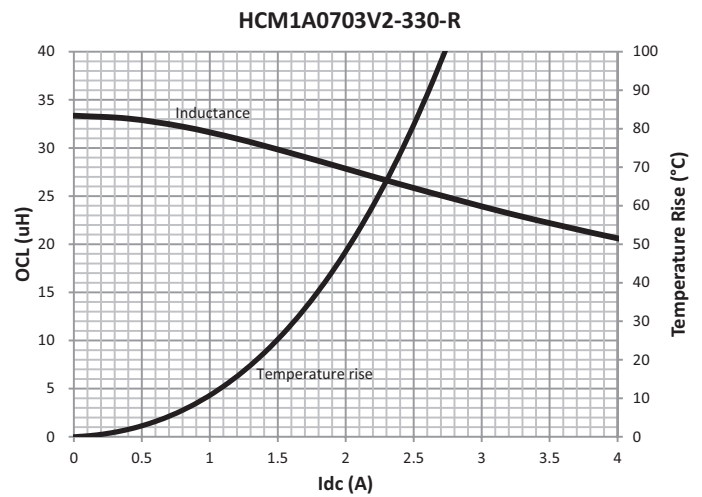
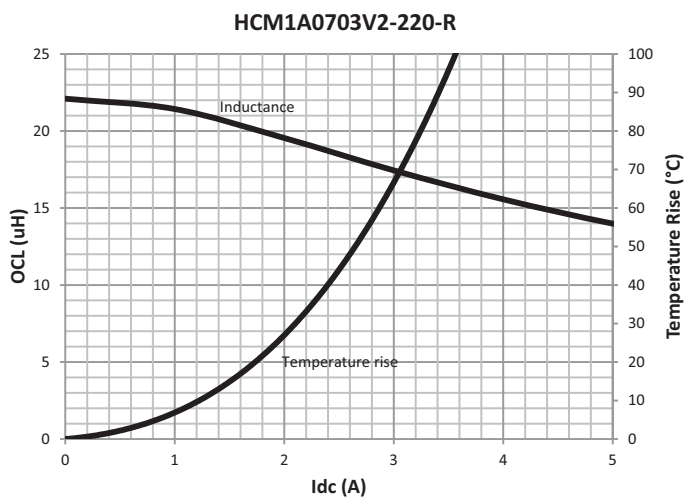
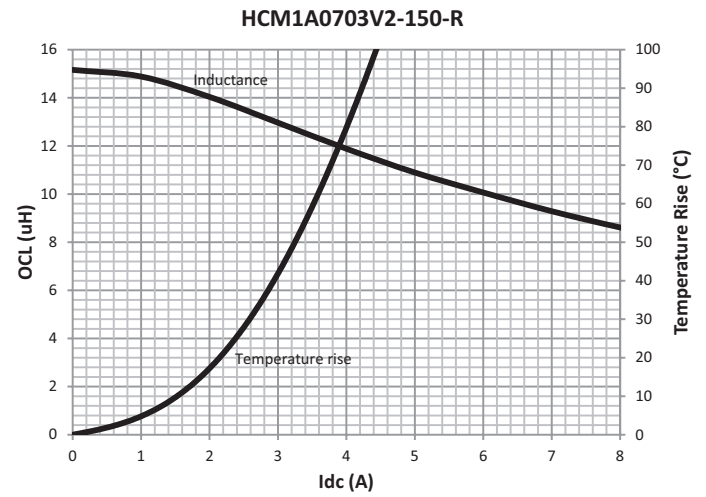
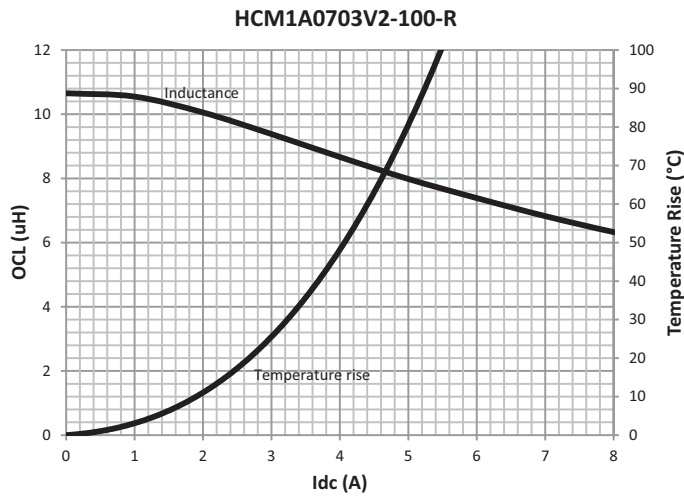
Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Solder reflow profile

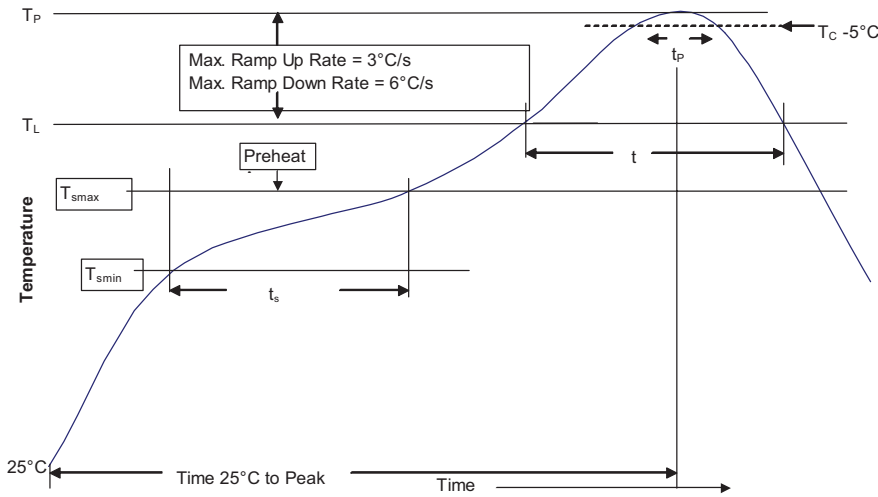


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3 °C/ Second Max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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